Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info	Subsectionals *	A-D
	Manufacturing Info		* : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-05-24
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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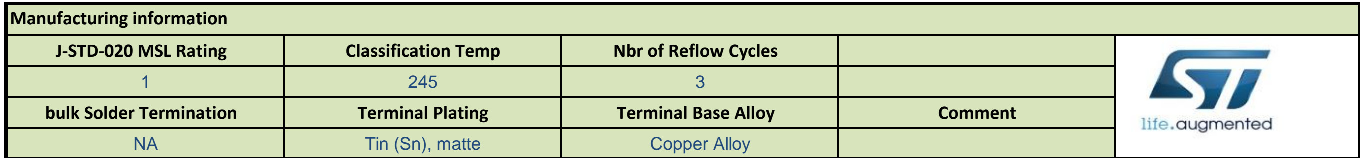
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STPSC8H065G2Y-TR	BT(9*3D13AT6	A	3068	2018-05-24
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	1380	mg	Each	ECOPACK2
,	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
1	245	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-7.2-4.5	3	GULL WING	
Comment	H2PAK HC 2-3 Leads			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**TRUE**
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 15th December 2017			
Query			**Response**
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			**FALSE**
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			**TRUE**
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.24	Die - Leadframe	177
Lead	2.04	Soft solder	1477

QueryList : REACH-15th January 2018				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration :
note : Substance present with less 0.001mg will not be declared in this document

Mfr Item Name: BT(9*3D13AT6

Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.502	mg	supplier	die	Silicium carbide	409-21-2		3.402	mg	971445	2465
				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	5711	14
				supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	855	3
				supplier	metallization	Nickel (Ni)	7440-02-0		0.016	mg	4569	12
				supplier	metallization	Silver (Ag)	7440-22-4		0.033	mg	9423	24
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	286	1
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	286	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	857	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.014	mg	3998	10
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.009	mg	2570	7
Leadframe	M-004 Copper and its alloys	848.010	mg	supplier	alloy	Copper (Cu)	7440-50-8		846.677	mg	998428	613534
				supplier	alloy	Iron (Fe)	7439-89-6		0.848	mg	1000	614
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.254	mg	300	184
				supplier	metallization	Nickel (Ni)	7440-02-0		0.214	mg	252	155
				supplier	metallization	Phosphorus (P)	7723-14-0		0.017	mg	20	12
Soft solder	Solder	2.134	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	2.038	mg	955014	1477
				supplier	solder	Silver (Ag)	7440-22-4		0.053	mg	24836	38
				supplier	solder	Tin (Sn)	7440-31-5		0.043	mg	20150	31
Bonding wires	M-003 Aluminum and its alloys	1.385	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.385	mg	1000000	1004
Encapsulation	M-011 Other inorganic materials	521.235	mg	supplier	mold compound	Silica, vitreous	60676-86-0		456.081	mg	875001	330493
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-bi	EC 413-900-7		20.849	mg	39999	15108
				supplier	mold compound	Epoxy Resin	25068-38-6		15.637	mg	30000	11331
				supplier	mold compound	phenol resin	29690-82-2		26.062	mg	50000	18886
				supplier	mold compound	Carbon black	1333-86-4		2.606	mg	5000	1888
connections coating	Solder	3.734	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.734	mg	1000000	2706